

10BASE-T NETWORK COMPONENTS

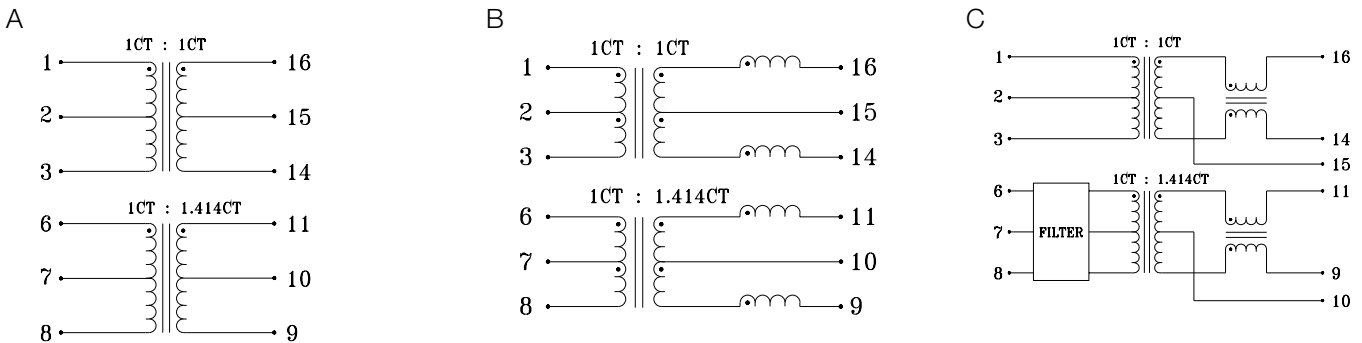
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- Designed for use with Level One 10Base-T chipset LXT901 LXT907, LXT914 or Texas Instruments Quad PHY (TNETE 2004)
- 1:1 or 1:√2 turns ratio on transmit, 1:1 turns ratio on receive
- Single port components, available with and without common mode chokes
- Through-hole and surface mount packaging
- Models with additional differential filtering available
- 2000 Vrms isolation

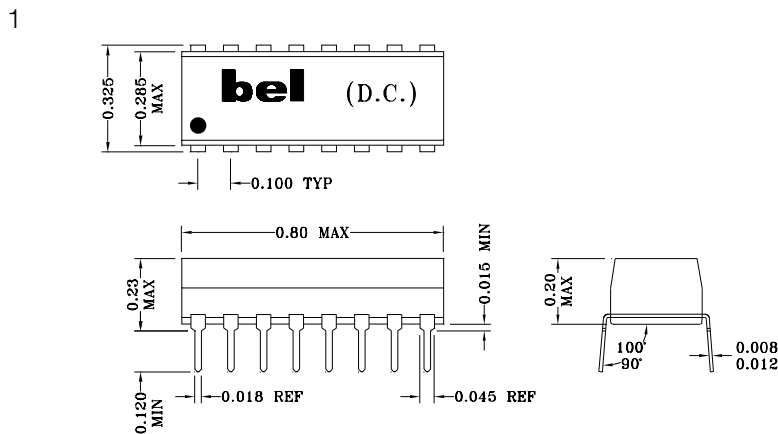
ELECTRICALS AT 25°C

Part No.	Insertion Loss (dB) Max		Return Loss (dB) Min	Crosstalk (dB) Min	Attenuation (dB) Min			CM-CM Rej (dB) Min		Package Style
	1-10MHz	10-100MHz			1-10MHz	1MHz-10MHz	25	30	40	
A553-0716-00	-1.0	140	-18	-40	N/A	N/A	N/A	A	1	
A553-5999-64	-1.0	200	-18	-40	N/A	N/A	N/A	A	1	
S553-0716-00	-1.0	140	-18	-40	N/A	N/A	N/A	A	2	
S553-5999-08	-1.0	110	-15	-40	N/A	-40	-30	B	2	
S556-5999-26	-1.0	110	-15	-40	-5	-10	-16	C	2	
S556-5999-53	-1.0	110	-15	-40	-5	-10	-16	C	3	

SCHEMATICS



MECHANICALS



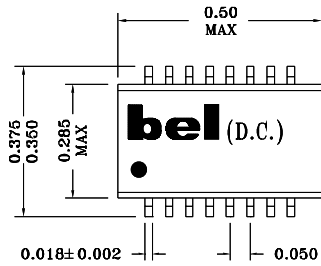
Specifications subject to change without notice.

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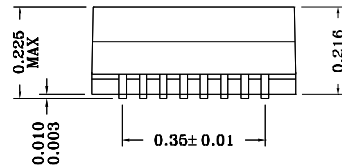
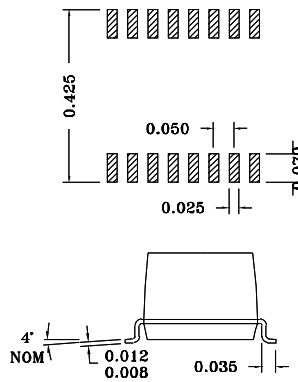
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MECHANICALS (CONT'D)

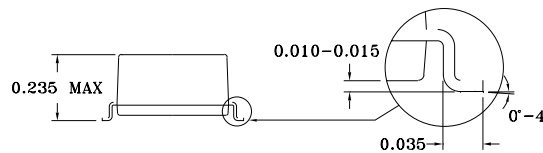
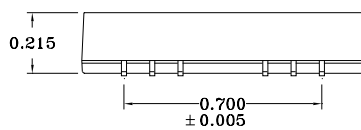
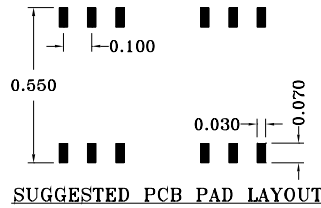
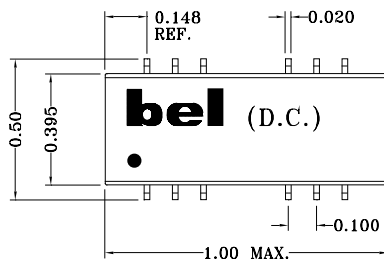
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SUGGESTED PCB PAD LAYOUT



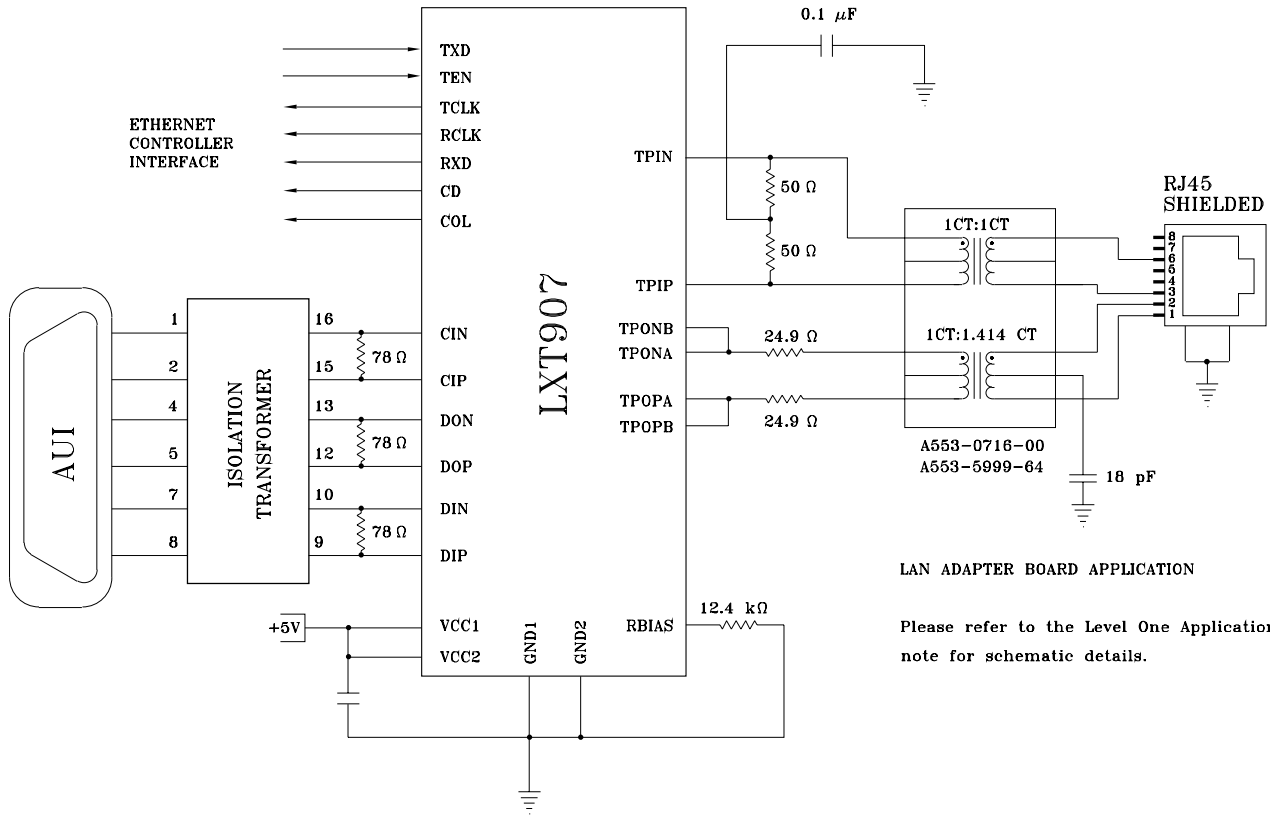
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APPLICATION CIRCUIT



LAN ADAPTER BOARD APPLICATION

Please refer to the Level One Application note for schematic details.

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defining a degree of excellence

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APPLICATION NOTES

- All designs meet IEEE 802.3 standards.
- Models with additional differential filtering are typically used in high density, multi-port applications or high noise content adapter cards.
- Bel's low profile, surface mount packaging is ideal for high speed pick and place machinery. Parts can be shipped on tape and reel for high speed placement. Construction processes have been implemented for thermal compatibility with high temperature IR reflow assembly processing. Post dipping of leads assist with PC board solderability. Each part is optically inspected to meet rigid coplanarity requirements.

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